Gluing tests Carbon fiber + fanout Kapton

M. Almanza Soto, A. Irles, C. Orero 17/04/2025



















Material available

- Received at IFIC from TAU:
 - 19 Fanouts
 - 21 High Voltage Kapton PCB
- Sent from IFIC to AGH U. Krakow:
 - 2 Fanouts

- Available at IFIC:
 - 17 Fanouts
 - 21 High Voltage Kapton PCB
 - 20 Carbon fiber for CSIS (machined in external company WorkShape)
 - 15 Carbon fiber for tests (from ClipCarbono)

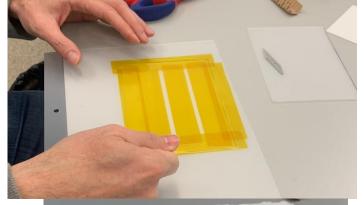


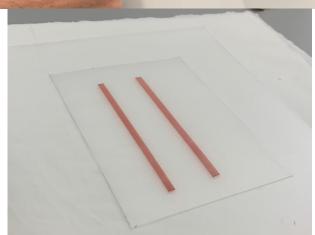
Carbon fiber + fanout tests



Kapton tape stencil + silicone glue

- Spread silicone with a blade
- Thin silicone layer
- Clean edges
- Hard to manipulate Kapton tape
- Hard to position tape

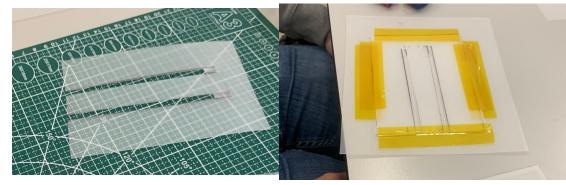






Plastic stencil +Silicone Glue

- Easy to position
- Clean edges

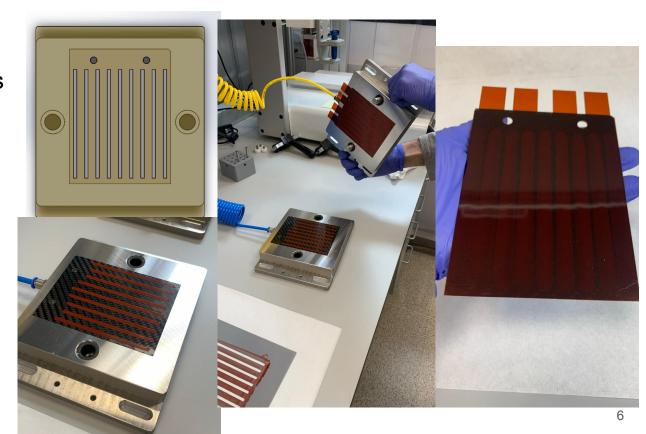






3D Printed stencil + silicone glue

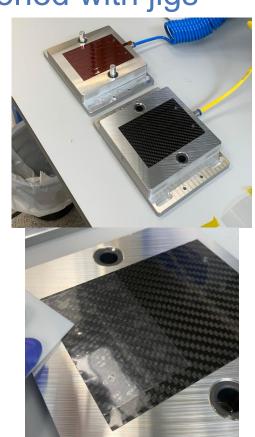
- Worked very well
- Stencil aligned with pins
- Straight lines
- Cleaning stencil is time consuming and messy (lots of wipes)
- Jig positioned and pressed
- Good results and no air bubbles
- 3 units ready to assemble CSIS

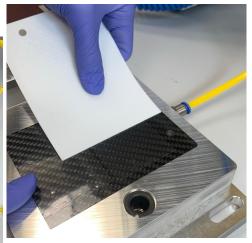


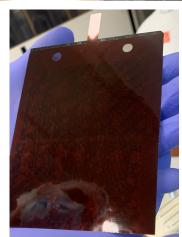


Double sided tape positioned with jigs

- Easy to position
- Air bubbles between CF and tape and between tape and Kapton FO
- Good precision in CF-FO placement because of the use of jigs
- Bonds strongly to both materials









Samples for heating tests

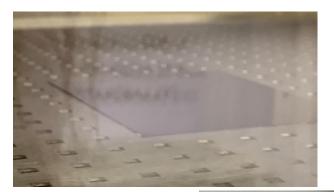
- 1. CF+Fake Kapton FO+Double sided tape
- 2. CF+dummy Kapton FO+silicone

Heating cycle: 80 minutes 140 degrees->cooling in oven after cycle



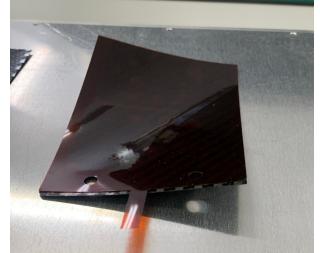
Results 1: CF+Fake Kapton FO+Double sided tape

While heating->OK



Better adhesion to materials after heating (from peel tests)

After cooling->Completely deformed





Results 2: CF+dummy Kapton FO+silicone

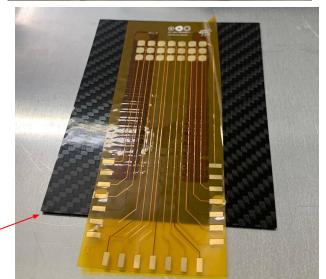
While heating-> Slightly warped in one direction



After cooling-> Slightly warped in the other direction

Better adhesion to materials after heating (from peel tests)

Notice bent

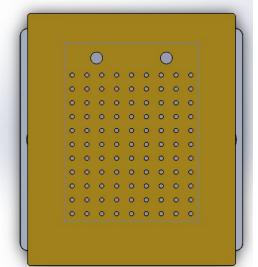




Solution?

Stencil to deposit silicone circles instead of strips

Results next->







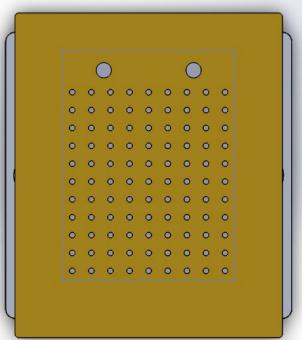
Solution? Not exactly

Stencil to deposit silicone circles instead of strips

Fake fanout + CF

Bent completely during regular curing cycle







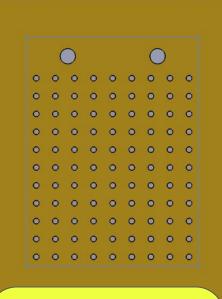
Solution? Not exactly

Stencil to deposit silicone circles instead of strips

Fake fanout + CF

Bent completely during regular curing cycle





Conclusion:
Differences in the thermal expansion of FO,CF and silicone glue



Fake CSIS tests

Tests performed to set the final CSIS glueing procedure in clean room.

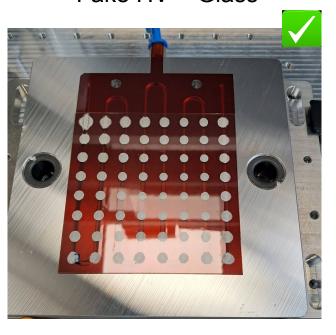
Layers:

- Carbon fiber Silicone glue (slide 5)
- Fake fanout (kapton 125 microns no pads)
- Glass 700 micron ← H20
- Fake High voltage (kapton 125 microns no pad)
- Oven cycle:
 - 30 minutes at 50 degrees
 - 30 minutes at 80 degrees
 - 4 hours at 100 degrees

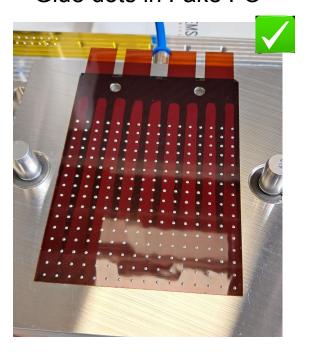


Fake CSIS tests

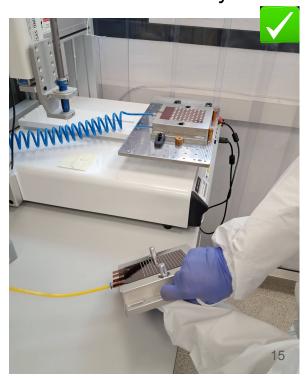
Fake HV + Glass



Glue dots in Fake FO



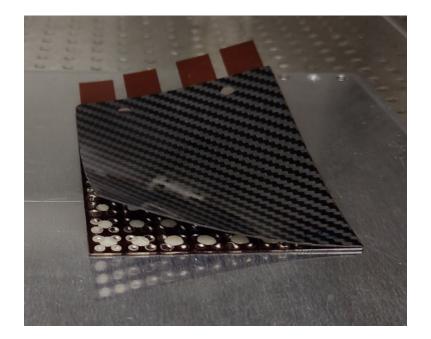
CSIS assembly





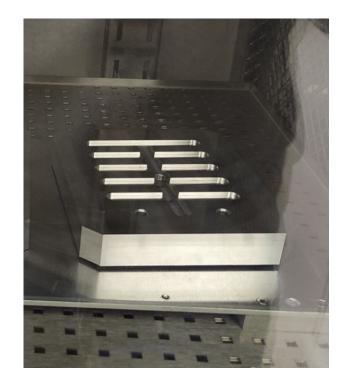
After a few minutes in the oven

- CF+Fake FO with silicone->Bent
- Glue dots were the right size
- Fake HV did not bend





- Added some weight after noticing bending
- After full curing cycle the CSIS is flat

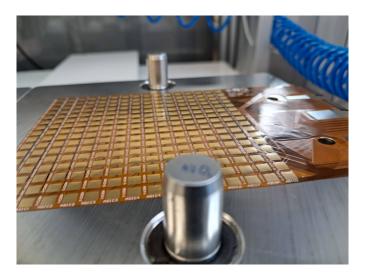




Open question from tests

- Will the bending happen with real FANOUT?
- Can we put wet silicone glue in the oven to prevent bending?

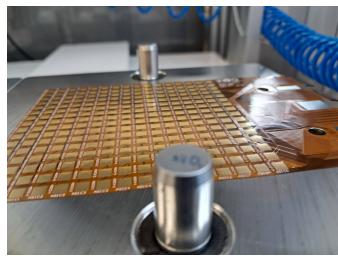
Answer next

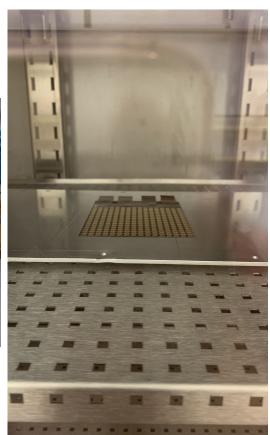




Real fanout + CF + wet silicone



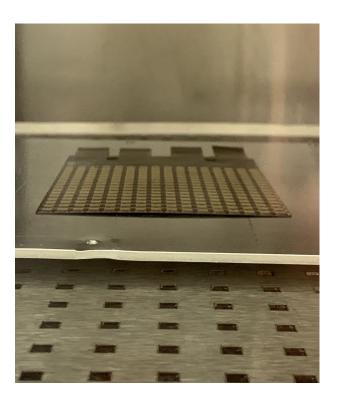






Results: bending

Bending started at 67 degrees





Results: bending

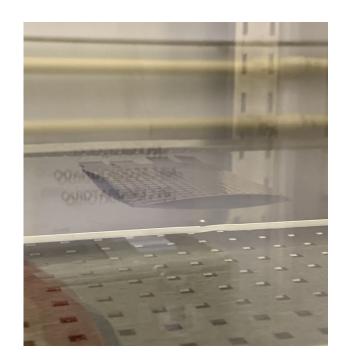
At 78 degrees





Results: bending

At 100 degrees





Conclusions

- Any pre-gluing of carbon fiber to fanout will result in bending from differences in material thermal expansion.
- Can be reduced by keeping CSIS in jig or with weights to flatten but it is risky to put weight with wet H20 glue, the least manipulation the better.
- Possible solutions:
 - Use H20 in all layers and cure once
 - Glue carbon fiber after curing (preferred option)



Next week

- 1. Glass CSIS with CF gluing after curing
- 2. Real CSIS with the best CF gluing method
 - a. Number to be defined
 - b. No PCB design for CSIS testing